

METHOD OF PRESSURE CURING FOR REDUCING VOIDS IN A DIE
ATTACH BONDLINE AND APPLICATIONS THEREOF

ABSTRACT OF THE DISCLOSURE

A method of curing adhesives of a die attach material to reduce the formation of voids at the resulting bondline, defined by the interface between the adhesive and the surface of a die being attached. The method includes applying a relatively high pressure, in addition to a relatively high temperature, to cure the adhesive material.

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